



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Kinsman et al.

**Serial No.:** 10/624,833

**Filed:** July 22, 2003

**For:** METHOD FOR FABRICATING A  
CHIP SCALE PACKAGE USING WAFER  
LEVEL PROCESSING (as amended)

**Confirmation No.:** 6568

**Examiner:** M. Estrada

**Group Art Unit:** 2823

**Attorney Docket No.:** 2269-3572.2US  
(97-1243.02/US)

**Notice of Allowance Mailed:**

November 19, 2004

**Express Mail Mailing Label No.:** EL 994826070 US

**Date of Deposit with USPS:** February 15, 2005

**Person making Deposit:** Steve Wong

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

*Please  
enter  
O.C.  
3/15/2005*